DE LA RECHERCHE À L'INDUSTRIE



Soldered Aluminum conductor: A backup solution?

Saclay experience

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It was 20 years ago



www.cea.fr



OUTLINE

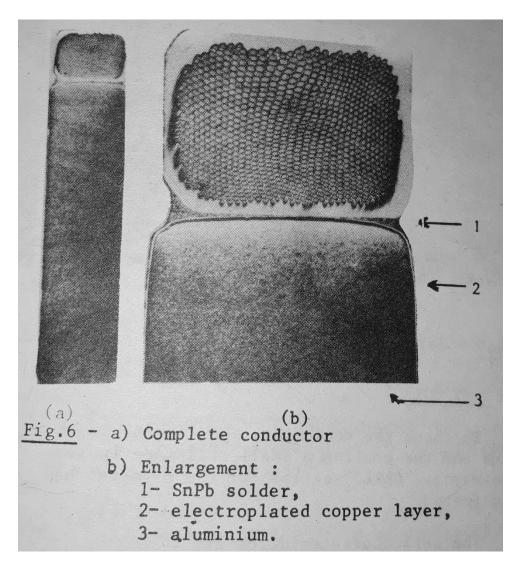


- Historical: old work done at Saclay
- General consideration
- Conclusions



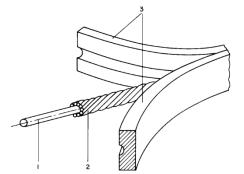
FIRST LARGE TRANSPARENT MAGNET





One of the first aluminum soldered conductor 1979 for a solenoid of 1.5 T (\emptyset_i = 1.6 m, length 4 m).

One year after Morpurgo magnet





CMS / ATLAS R&D FIRST MOCK UP





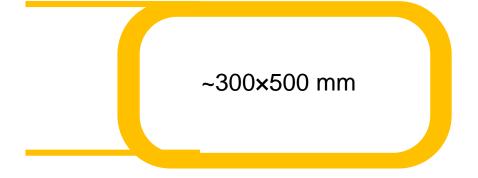
Existing Al. stabilizer with copper deposition



Groove machined by Turck head



Existing Rutherford & soldering by hand



Quench studies & inductive heater

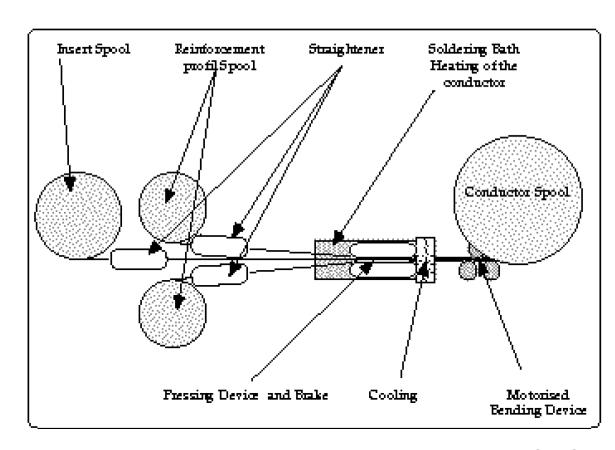
~2×5 mm

First ATLAS Ractrack (MicroB)



CMS SOLDERING FIRST TRIAL





Principe of the reinforcement soldering line of CMS (Back up solution)

Electrolytic copper deposition was made by PEM (F).

Reinforcement the has been solder by hand at Saclay: old geometry (5+5)*70 mm².

Cream solder with flux has been tested; but number of bubbles (due to the flux) were trapped between pieces.

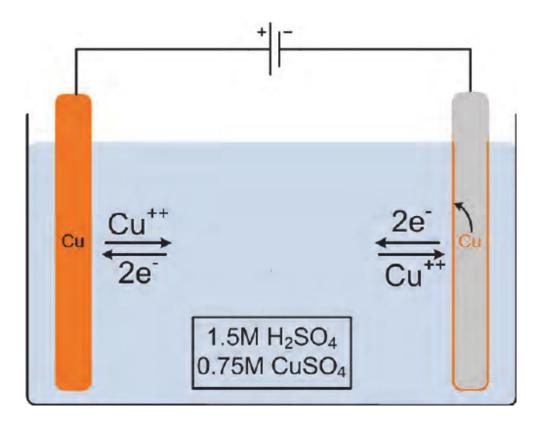
Wave solder, Ultra sonic solder bath and vertical position would improve the soldering process by removing most of bubbles.

Temperatures (including gradient) and time must be set carefully.



COPPER ELECTROLYTIC DEPOSITION ON AL.





Standard copper electrodeposition

To make a good electrolytic copper deposition on aluminum you need to remove the Al_2O_3 oxidation of the external surface of your piece.

As Al. oxidation get very fast in air, the usual solution is to use one bath with the etching of Al. and the Cu2+ cation together in solution.

It takes TIME!



Deposit locally by tampon



ISSUES

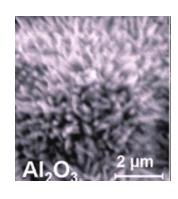


Electrodeposition:

One, we get Al₂O₃ filaments up to 2 cm due to material (toxic) use in the flux and the presence of humidity...

Soft soldering:

- Presence of flux in the remaining bubbles.
- Large possibility of oxidation: black spot, yellow, green, white ...
- Local backup solution is need in case of lake of soldering.
- "Poor" bonding quality (~25 MPa) but not so different than pure Al. Thermal contraction Al./Cu gives already 10 MPa.

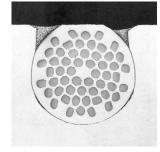












Crimped Wire In Channel



COPPER CLAD WIRE





An alternative more industrial method is to place a coper tube around aluminum cylinder and to draw the overall.

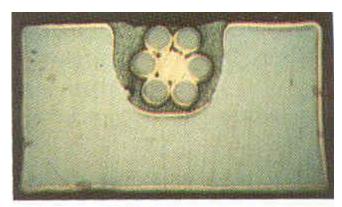
With a large section reduction the oxidation is dilute on the wire surface and good bounding is obtain.

Cladding process can also be continuous: welding tube around wire.

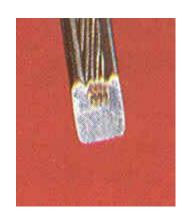


CONDUCTOR EXAMPLES





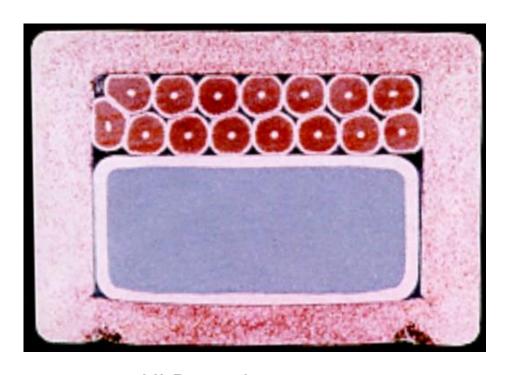
6+1 in Channel (Not crimping!)



Cu deposit or direct soldering?



HTS!



HLD conductor (CuNi2% clad)



GD (US) GE (US) Japan

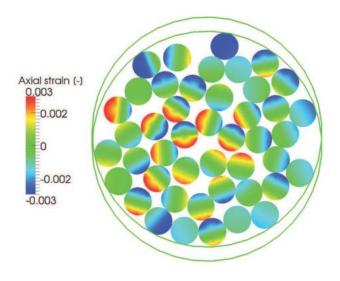
CERN workshop- 12-14/09/2022



SUMMARY



- Cu electrodeposition is possible but quite expensive.
- Clad coating is an alternative (more coper).
- Do we need soldering? We need:
 - Mechanical support.
 - Electrical and thermal contact.



Transverse cross-section of a cable submitted to 50 kN/m transverse compression.

Numerical simulation of the mechanical behavior of the ITER cable-in-conduit conductors, Hugues Bajas



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